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What is "Embedded - Microcontrollers"?

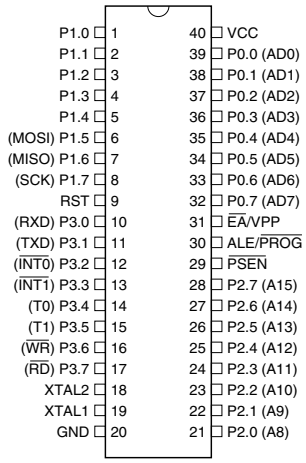
"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

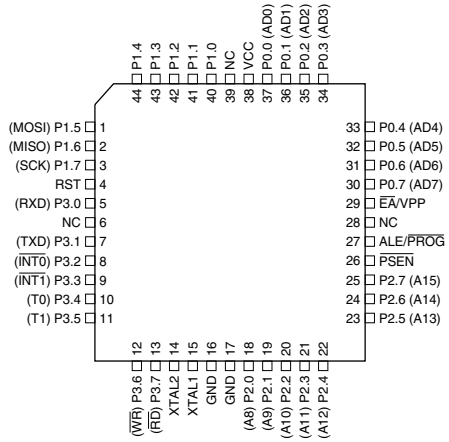
Details	
Product Status	Obsolete
Core Processor	8051
Core Size	8-Bit
Speed	16MHz
Connectivity	UART/USART
Peripherals	WDT
Number of I/O	32
Program Memory Size	4KB (4K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	128 x 8
Voltage - Supply (Vcc/Vdd)	2.7V ~ 4V
Data Converters	-
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	44-TQFP
Supplier Device Package	44-TQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/at89ls51-16ai

2. Pin Configurations

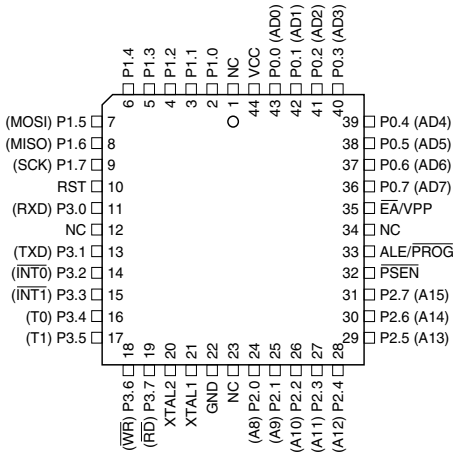
2.1 40-lead PDIP



2.2 44-lead TQFP



2.3 44-lead PLCC



4.6 Port 3

Port 3 is an 8-bit bidirectional I/O port with internal pull-ups. The Port 3 output buffers can sink/source four TTL inputs. When 1s are written to Port 3 pins, they are pulled high by the internal pull-ups and can be used as inputs. As inputs, Port 3 pins that are externally being pulled low will source current (I_{IL}) because of the pull-ups.

Port 3 receives some control signals for Flash programming and verification.

Port 3 also serves the functions of various special features of the AT89LS51, as shown in the following table.

Port Pin	Alternate Functions
P3.0	RXD (serial input port)
P3.1	TXD (serial output port)
P3.2	$\overline{\text{INT0}}$ (external interrupt 0)
P3.3	$\overline{\text{INT1}}$ (external interrupt 1)
P3.4	T0 (timer 0 external input)
P3.5	T1 (timer 1 external input)
P3.6	$\overline{\text{WR}}$ (external data memory write strobe)
P3.7	$\overline{\text{RD}}$ (external data memory read strobe)

4.7 RST

Reset input. A high on this pin for two machine cycles while the oscillator is running resets the device. This pin drives High for 98 oscillator periods after the Watchdog times out. The DISRTO bit in SFR AUXR (address 8EH) can be used to disable this feature. In the default state of bit DISRTO, the RESET HIGH out feature is enabled.

4.8 ALE/$\overline{\text{PROG}}$

Address Latch Enable (ALE) is an output pulse for latching the low byte of the address during accesses to external memory. This pin is also the program pulse input ($\overline{\text{PROG}}$) during Flash programming.

In normal operation, ALE is emitted at a constant rate of 1/6 the oscillator frequency and may be used for external timing or clocking purposes. Note, however, that one ALE pulse is skipped during each access to external data memory.

If desired, ALE operation can be disabled by setting bit 0 of SFR location 8EH. With the bit set, ALE is active only during a MOVX or MOVC instruction. Otherwise, the pin is weakly pulled high. Setting the ALE-disable bit has no effect if the microcontroller is in external execution mode.

4.9 $\overline{\text{PSEN}}$

Program Store Enable ($\overline{\text{PSEN}}$) is the read strobe to external program memory.

When the AT89LS51 is executing code from external program memory, $\overline{\text{PSEN}}$ is activated twice each machine cycle, except that two $\overline{\text{PSEN}}$ activations are skipped during each access to external data memory.

4.10 $\overline{EA}$/VPP

External Access Enable. $\overline{EA}$ must be strapped to GND in order to enable the device to fetch code from external program memory locations starting at 0000H up to FFFFH. Note, however, that if lock bit 1 is programmed, $\overline{EA}$ will be internally latched on reset.

$\overline{EA}$ should be strapped to V_{CC} for internal program executions.

This pin also receives the 12-volt programming enable voltage (V_{PP}) during Flash programming.

4.11 XTAL1

Input to the inverting oscillator amplifier and input to the internal clock operating circuit.

4.12 XTAL2

Output from the inverting oscillator amplifier

5. Special Function Registers

A map of the on-chip memory area called the Special Function Register (SFR) space is shown in Table 5-1.

Note that not all of the addresses are occupied, and unoccupied addresses may not be implemented on the chip. Read accesses to these addresses will in general return random data, and write accesses will have an indeterminate effect.

Table 5-2. AUXR: Auxiliary Register

AUXR Address = 8EH Reset Value = XXX00XX0B

Not Bit Addressable

	–	–	–	WDIDLE	DISRTO	–	–	DISALE
Bit	7	6	5	4	3	2	1	0

–	Reserved for future expansion	
DISALE	Disable/Enable ALE	
	DISALE Operating Mode	
	0	ALE is emitted at a constant rate of 1/6 the oscillator frequency
	1	ALE is active only during a MOVX or MOVC instruction
DISRTO	Disable/Enable Reset out	
	DISRTO	
	0	Reset pin is driven High after WDT times out
	1	Reset pin is input only
WDIDLE	Disable/Enable WDT in IDLE mode	
	WDIDLE	
	0	WDT continues to count in IDLE mode
	1	WDT halts counting in IDLE mode

Dual Data Pointer Registers: To facilitate accessing both internal and external data memory, two banks of 16-bit Data Pointer Registers are provided: DP0 at SFR address locations 82H-83H and DP1 at 84H-85H. Bit DPS = 0 in SFR AUXR1 selects DP0 and DPS = 1 selects DP1. The user should **always** initialize the DPS bit to the appropriate value before accessing the respective Data Pointer Register.

Power Off Flag: The Power Off Flag (POF) is located at bit 4 (PCON.4) in the PCON SFR. POF is set to “1” during power up. It can be set and rest under software control and is not affected by reset.

7.1 Using the WDT

To enable the WDT, a user must write 01EH and 0E1H in sequence to the WDTRST register (SFR location 0A6H). When the WDT is enabled, the user needs to service it by writing 01EH and 0E1H to WDTRST to avoid a WDT overflow. The 14-bit counter overflows when it reaches 16383 (3FFFH), and this will reset the device. When the WDT is enabled, it will increment every machine cycle while the oscillator is running. This means the user must reset the WDT at least every 16383 machine cycles. To reset the WDT the user must write 01EH and 0E1H to WDTRST. WDTRST is a write-only register. The WDT counter cannot be read or written. When WDT overflows, it will generate an output RESET pulse at the RST pin. The RESET pulse duration is 98xTOSC, where TOSC=1/FOSC. To make the best use of the WDT, it should be serviced in those sections of code that will periodically be executed within the time required to prevent a WDT reset.

7.2 WDT During Power-down and Idle

In Power-down mode the oscillator stops, which means the WDT also stops. While in Power-down mode, the user does not need to service the WDT. There are two methods of exiting Power-down mode: by a hardware reset or via a level-activated external interrupt, which is enabled prior to entering Power-down mode. When Power-down is exited with hardware reset, servicing the WDT should occur as it normally does whenever the AT89LS51 is reset. Exiting Power-down with an interrupt is significantly different. The interrupt is held low long enough for the oscillator to stabilize. When the interrupt is brought high, the interrupt is serviced. To prevent the WDT from resetting the device while the interrupt pin is held low, the WDT is not started until the interrupt is pulled high. It is suggested that the WDT be reset during the interrupt service for the interrupt used to exit Power-down mode.

To ensure that the WDT does not overflow within a few states of exiting Power-down, it is best to reset the WDT just before entering Power-down mode.

Before going into the IDLE mode, the WDIDLE bit in SFR AUXR is used to determine whether the WDT continues to count if enabled. The WDT keeps counting during IDLE (WDIDLE bit = 0) as the default state. To prevent the WDT from resetting the AT89LS51 while in IDLE mode, the user should always set up a timer that will periodically exit IDLE, service the WDT, and reenter IDLE mode.

With WDIDLE bit enabled, the WDT will stop to count in IDLE mode and resumes the count upon exit from IDLE.

8. UART

The UART in the AT89LS51 operates the same way as the UART in the AT89C51. For further information on the UART operation, please click on the document link below:

http://www.atmel.com/dyn/resources/prod_documents/DOC4316.PDF

9. Timer 0 and 1

Timer 0 and Timer 1 in the AT89LS51 operate the same way as Timer 0 and Timer 1 in the AT89C51. For further information on the timers' operation, please click on the document link below:

http://www.atmel.com/dyn/resources/prod_documents/DOC4316.PDF

10. Interrupts

The AT89LS51 has a total of five interrupt vectors: two external interrupts ($\overline{INT0}$ and $\overline{INT1}$), two timer interrupts (Timers 0 and 1), and the serial port interrupt. These interrupts are all shown in Figure 10-1.

Each of these interrupt sources can be individually enabled or disabled by setting or clearing a bit in Special Function Register IE. IE also contains a global disable bit, EA, which disables all interrupts at once.

Note that Table 10-1 shows that bit positions IE.5 and IE.6 are unimplemented. User software should not write 1s to these bit positions, since they may be used in future AT89 products.

The Timer 0 and Timer 1 flags, TF0 and TF1, are set at S5P2 of the cycle in which the timers overflow. The values are then polled by the circuitry in the next cycle.

Table 10-1. Interrupt Enable (IE) Register

(MSB) (LSB)

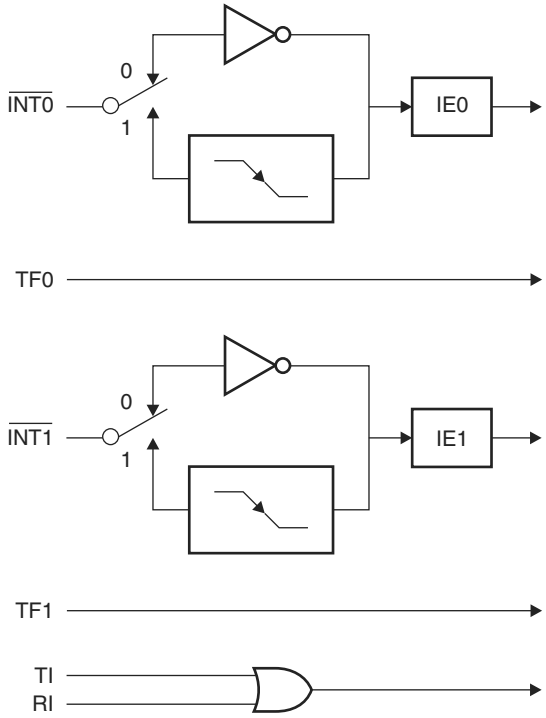
EA	–	–	ES	ET1	EX1	ET0	EX0

Enable Bit = 1 enables the interrupt.

Enable Bit = 0 disables the interrupt.

Symbol	Position	Function
EA	IE.7	Disables all interrupts. If EA = 0, no interrupt is acknowledged. If EA = 1, each interrupt source is individually enabled or disabled by setting or clearing its enable bit.
–	IE.6	Reserved
–	IE.5	Reserved
ES	IE.4	Serial Port interrupt enable bit
ET1	IE.3	Timer 1 interrupt enable bit
EX1	IE.2	External interrupt 1 enable bit
ET0	IE.1	Timer 0 interrupt enable bit
EX0	IE.0	External interrupt 0 enable bit
User software should never write 1s to reserved bits, because they may be used in future AT89 products.		

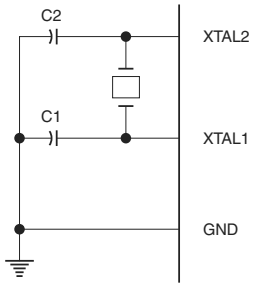
Figure 10-1. Interrupt Sources



11. Oscillator Characteristics

XTAL1 and XTAL2 are the input and output, respectively, of an inverting amplifier that can be configured for use as an on-chip oscillator, as shown in Figure 11-1. Either a quartz crystal or ceramic resonator may be used. To drive the device from an external clock source, XTAL2 should be left unconnected while XTAL1 is driven, as shown in Figure 11-2. There are no requirements on the duty cycle of the external clock signal, since the input to the internal clocking circuitry is hrough a divide-by-two flip-flop, but minimum and maximum voltage high and low time specifications must be observed.

Figure 11-1. Oscillator Connections



Note: C1, C2 = 30 pF ±10 pF for Crystals
= 40 pF ±10 pF for Ceramic Resonators

5. At the end of a programming session, RST can be set low to commence normal device operation.

Power-off sequence (if needed):

1. Set XTAL1 to “L” (if a crystal is not used).
2. Set RST to “L”.
3. Turn V_{CC} power off.

Data Polling: The $\overline{\text{Data}}$ Polling feature is also available in the serial mode. In this mode, during a write cycle an attempted read of the last byte written will result in the complement of the MSB of the serial output byte on MISO.

16.2 Serial Programming Instruction Set

The Instruction Set for Serial Programming follows a 4-byte protocol and is shown in Table 19-1.

17. Programming Interface – Parallel Mode

Every code byte in the Flash array can be programmed by using the appropriate combination of control signals. The write operation cycle is self-timed and once initiated, will automatically time itself to completion.

Most major worldwide programming vendors offer support for the Atmel microcontroller series. Please contact your local programming vendor for the appropriate software revision.

Table 17-1. Flash Programming Modes

Mode	V_{CC}	RST	$\overline{\text{PSEN}}$	ALE/ $\overline{\text{PROG}}$	$\overline{\text{EA}}$/ V_{PP}	P2.6	P2.7	P3.3	P3.6	P3.7	P0.7-0 Data	P2.3-0 Address	P1.7-0 Address
Write Code Data	5V	H	L	(2)	12V	L	H	H	H	H	D_{IN}	A11-8	A7-0
Read Code Data	5V	H	L	H	H	L	L	L	H	H	D_{OUT}	A11-8	A7-0
Write Lock Bit 1	5V	H	L	(3)	12V	H	H	H	H	H	X	X	X
Write Lock Bit 2	5V	H	L	(3)	12V	H	H	H	L	L	X	X	X
Write Lock Bit 3	5V	H	L	(3)	12V	H	L	H	H	L	X	X	X
Read Lock Bits 1, 2, 3	5V	H	L	H	H	H	H	L	H	L	P0.2, P0.3, P0.4	X	X
Chip Erase	5V	H	L	(1)	12V	H	L	H	L	L	X	X	X
Read Atmel ID	5V	H	L	H	H	L	L	L	L	L	1EH	0000	00H
Read Device ID	5V	H	L	H	H	L	L	L	L	L	61H	0001	00H
Read Device ID	5V	H	L	H	H	L	L	L	L	L	06H	0010	00H

Notes:
1. Each $\overline{\text{PROG}}$ pulse is 200 ns - 500 ns for Chip Erase.
2. Each $\overline{\text{PROG}}$ pulse is 200 ns - 500 ns for Write Code Data.
3. Each $\overline{\text{PROG}}$ pulse is 200 ns - 500 ns for Write Lock Bits.
4. RDY/$\overline{\text{BSY}}$ signal is output on P3.0 during programming.
5. X = don’t care.

Figure 17-1. Programming the Flash Memory (Parallel Mode)

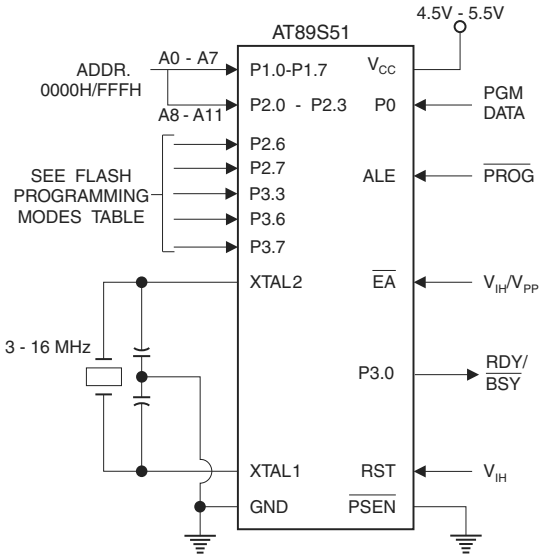
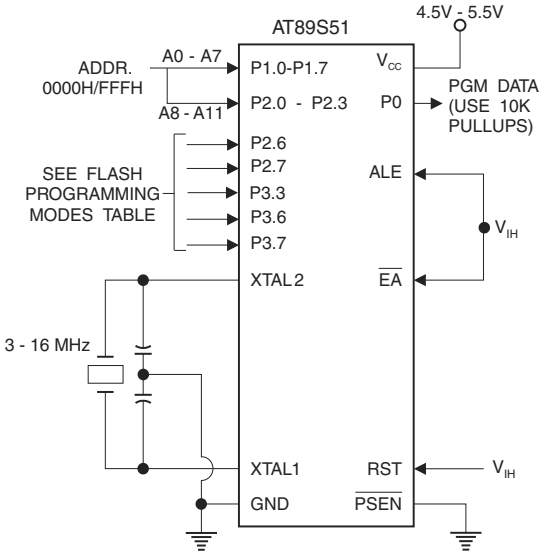


Figure 17-2. Verifying the Flash Memory (Parallel Mode)



18. Flash Programming and Verification Characteristics (Parallel Mode)

T_A = 20°C to 30°C, V_{CC} = 4.5 to 5.5V

Symbol	Parameter	Min	Max	Units
V_{PP}	Programming Supply Voltage	11.5	12.5	V
I_{PP}	Programming Supply Current		10	mA
I_{CC}	V_{CC} Supply Current		30	mA
$1/t_{CLCL}$	Oscillator Frequency	3	16	MHz
t_{AVGL}	Address Setup to $\overline{PROG}$ Low	48 t_{CLCL}		
t_{GHAX}	Address Hold After $\overline{PROG}$	48 t_{CLCL}		
t_{DVGL}	Data Setup to $\overline{PROG}$ Low	48 t_{CLCL}		
t_{GHDX}	Data Hold After $\overline{PROG}$	48 t_{CLCL}		
t_{EHSH}	P2.7 ($\overline{ENABLE}$) High to V_{PP}	48 t_{CLCL}		
t_{SHGL}	V_{PP} Setup to $\overline{PROG}$ Low	10		µs
t_{GHSL}	V_{PP} Hold After $\overline{PROG}$	10		µs
t_{GLGH}	$\overline{PROG}$ Width	0.2	1	µs
t_{AVQV}	Address to Data Valid		48 t_{CLCL}	
t_{ELQV}	$\overline{ENABLE}$ Low to Data Valid		48 t_{CLCL}	
t_{EHQZ}	Data Float After $\overline{ENABLE}$	0	48 t_{CLCL}	
t_{GHBL}	$\overline{PROG}$ High to $\overline{BUSY}$ Low		1.0	µs
t_{WC}	Byte Write Cycle Time		50	µs

Figure 18-1. Flash Programming and Verification Waveforms – Parallel Mode

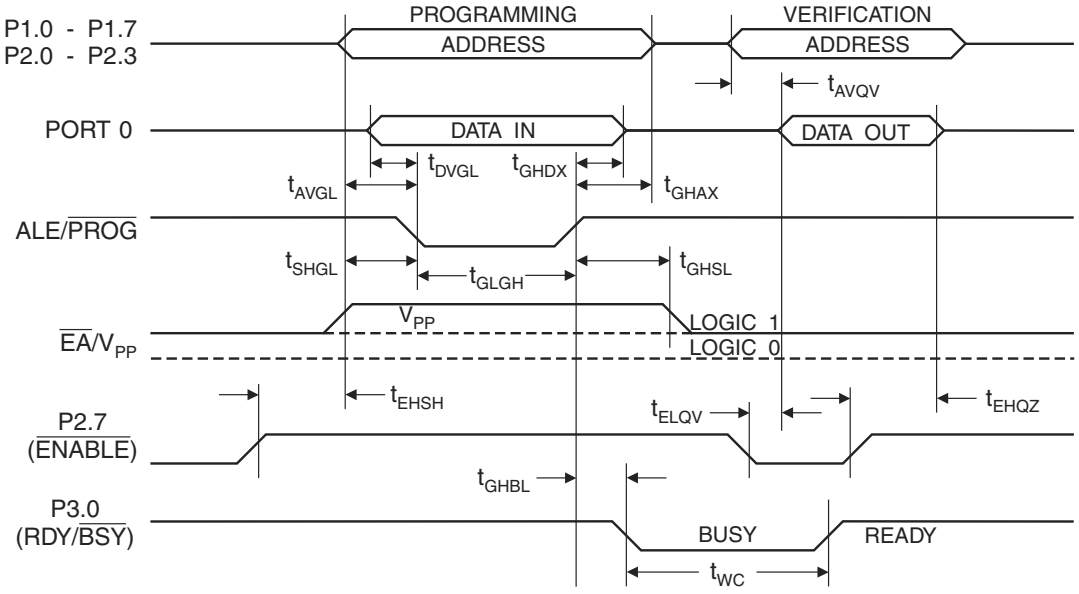
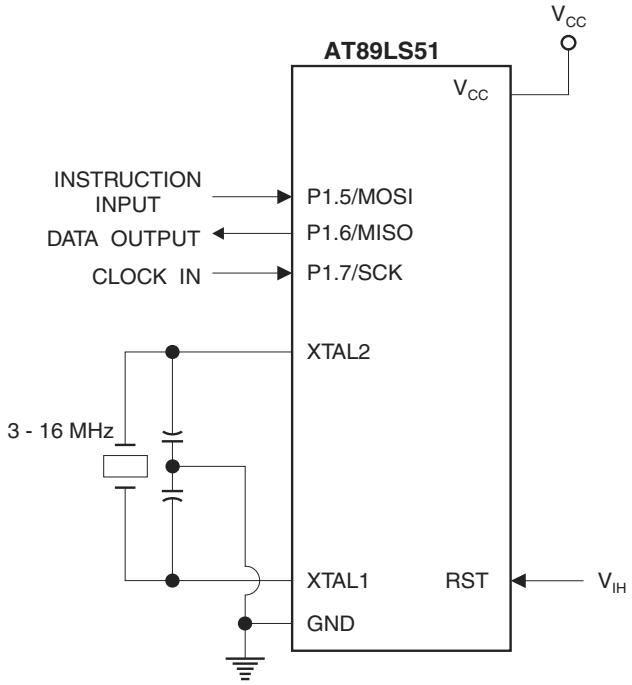
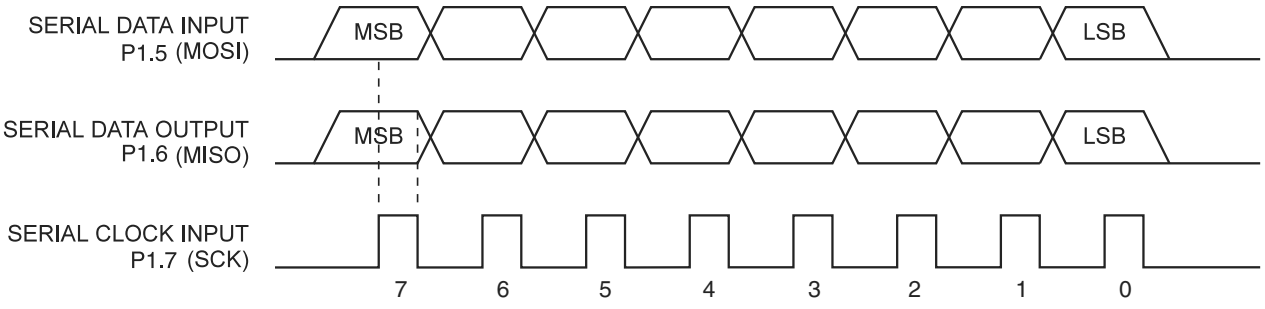


Figure 18-2. Flash Memory Serial Downloading



19. Flash Programming and Verification Waveforms – Serial Mode

Figure 19-1. Serial Programming Waveforms



20. Serial Programming Characteristics

Figure 20-1. Serial Programming Timing

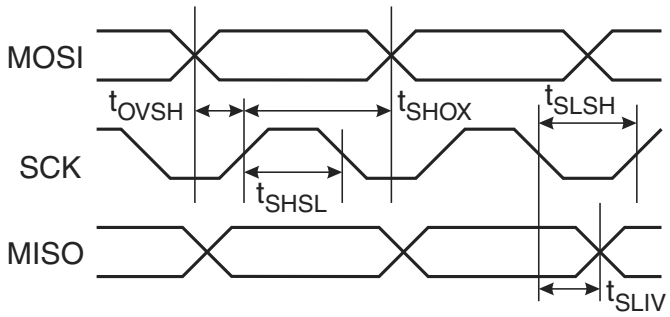


Table 20-1. Serial Programming Characteristics, T_A = -40· C to 85· C, V_{CC} = 2.7V - 4.0V (Unless Otherwise Noted)

Symbol	Parameter	Min	Typ	Max	Units
$1/t_{CLCL}$	Oscillator Frequency	3		16	MHz
t_{CLCL}	Oscillator Period	62.5			ns
t_{SHSL}	SCK Pulse Width High	8 t_{CLCL}			ns
t_{SLSH}	SCK Pulse Width Low	8 t_{CLCL}			ns
t_{OVSH}	MOSI Setup to SCK High	t_{CLCL}			ns
t_{SHOX}	MOSI Hold after SCK High	2 t_{CLCL}			ns
t_{SLIV}	SCK Low to MISO Valid	10	16	32	ns
t_{ERASE}	Chip Erase Instruction Cycle Time			500	ms
t_{SWC}	Serial Byte Write Cycle Time			64 t_{CLCL} + 400	µs

21. Absolute Maximum Ratings*

Operating Temperature	-55°C to +125°C
Storage Temperature	-65°C to +150°C
Voltage on Any Pin with Respect to Ground	-1.0V to +7.0V
Maximum Operating Voltage	6.6V
DC Output Current	15.0 mA

*NOTICE: Stresses beyond those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

22. DC Characteristics

The values shown in this table are valid for T_A = -40°C to 85°C and V_{CC} = 2.7V to 4.0V, unless otherwise noted.

Symbol	Parameter	Condition	Min	Max	Units
V_{IL}	Input Low Voltage	(Except $\overline{EA}$)	-0.5	0.7	V
V_{IL1}	Input Low Voltage ($\overline{EA}$)		-0.5	0.2 V_{CC}-0.3	V
V_{IH}	Input High Voltage	(Except XTAL1, RST)	0.2 V_{CC}+0.9	V_{CC}+0.5	V
V_{IH1}	Input High Voltage	(XTAL1, RST)	0.7 V_{CC}	V_{CC}+0.5	V
V_{OL}	Output Low Voltage[1] (Ports 1,2,3)	I_{OL} = 0.8 mA		0.45	V
V_{OL1}	Output Low Voltage[1] (Port 0, ALE, $\overline{PSEN}$)	I_{OL} = 1.6 mA		0.45	V
V_{OH}	Output High Voltage (Ports 1,2,3, ALE, $\overline{PSEN}$)	I_{OH} = -60 µA	2.4		V
		I_{OH} = -25 µA	0.65 V_{CC}		V
		I_{OH} = -10 µA	0.80 V_{CC}		V
V_{OH1}	Output High Voltage (Port 0 in External Bus Mode)	I_{OH} = -800 µA	2.4		V
		I_{OH} = -300 µA	0.75 V_{CC}		V
		I_{OH} = -80 µA	0.9 V_{CC}		V
I_{IL}	Logical 0 Input Current (Ports 1,2,3)	V_{IN} = 0.45V		-50	µA
I_{TL}	Logical 1 to 0 Transition Current (Ports 1,2,3)	V_{IN} = 2V		-150	µA
I_{LI}	Input Leakage Current (Port 0, $\overline{EA}$)	0.45 < V_{IN} < V_{CC}		±10	µA
RRST	Reset Pulldown Resistor		50	300	KΩ
C_{IO}	Pin Capacitance	Test Freq. = 1 MHz, T_A = 25°C		10	pF
I_{CC}	Power Supply Current	Active Mode, 12 MHz		25	mA
		Idle Mode, 12 MHz		6.5	mA
	Power-down Mode[2]	V_{CC} = 4.0V		30	µA

Notes:
1. Under steady state (non-transient) conditions, I_{OL} must be externally limited as follows:
   Maximum I_{OL} per port pin: 10 mA
   Maximum I_{OL} per 8-bit port:
   Port 0: 26 mA Ports 1, 2, 3: 15 mA
   Maximum total I_{OL} for all output pins: 71 mA
   If I_{OL} exceeds the test condition, V_{OL} may exceed the related specification. Pins are not guaranteed to sink current greater than the listed test conditions.
2. Minimum V_{CC} for Power-down is 2V.

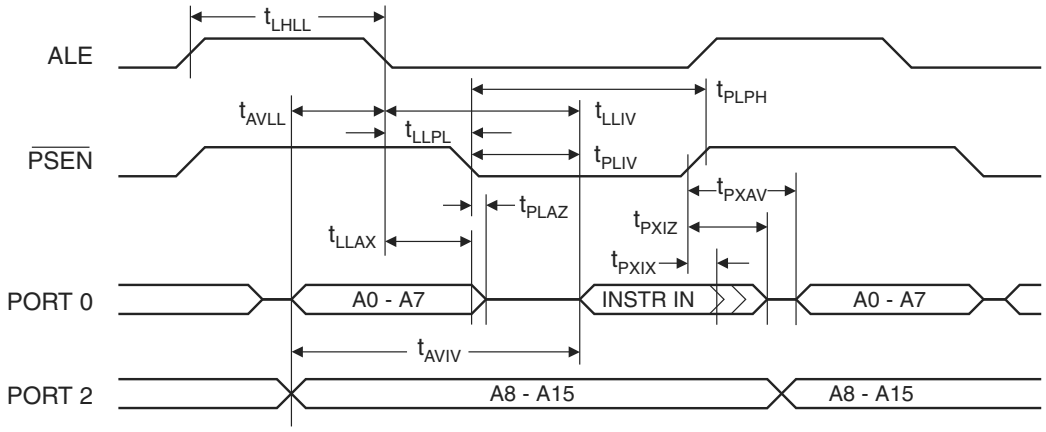
23. AC Characteristics

Under operating conditions, load capacitance for Port 0, ALE/$\overline{PROG}$, and $\overline{PSEN}$ = 100 pF; load capacitance for all other outputs = 80 pF.

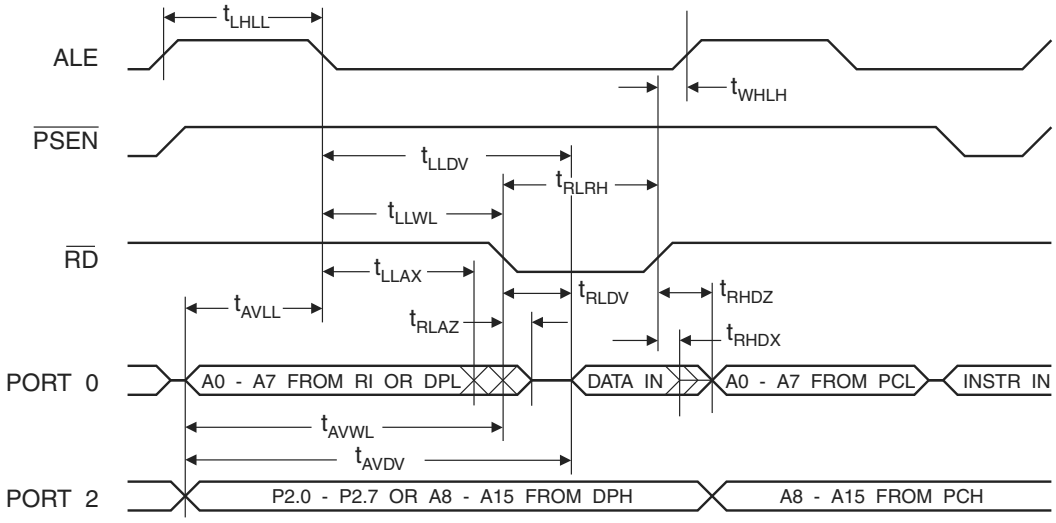
23.1 External Program and Data Memory Characteristics

Symbol	Parameter	16 MHz Oscillator		Variable Oscillator		Units
		Min	Max	Min	Max	
$1/t_{CLCL}$	Oscillator Frequency			0	16	MHz
t_{LHLL}	ALE Pulse Width	85		$2t_{CLCL}$-40		ns
t_{AVLL}	Address Valid to ALE Low	22		t_{CLCL}-40		ns
t_{LLAX}	Address Hold After ALE Low	32		t_{CLCL}-30		ns
t_{LLIV}	ALE Low to Valid Instruction In		150		$4t_{CLCL}$-100	ns
t_{LLPL}	ALE Low to $\overline{PSEN}$ Low	32		t_{CLCL}-30		ns
t_{PLPH}	$\overline{PSEN}$ Pulse Width	142		$3t_{CLCL}$-45		ns
t_{PLIV}	$\overline{PSEN}$ Low to Valid Instruction In		82		$3t_{CLCL}$-105	ns
t_{PXIX}	Input Instruction Hold After $\overline{PSEN}$	0		0		ns
t_{PXIZ}	Input Instruction Float After $\overline{PSEN}$		37		t_{CLCL}-25	ns
t_{PXAV}	$\overline{PSEN}$ to Address Valid	75		t_{CLCL}-8		ns
t_{AVIV}	Address to Valid Instruction In		207		$5t_{CLCL}$-105	ns
t_{PLAZ}	$\overline{PSEN}$ Low to Address Float		10		10	ns
t_{RLRH}	$\overline{RD}$ Pulse Width	275		$6t_{CLCL}$-100		ns
t_{WLWH}	$\overline{WR}$ Pulse Width	275		$6t_{CLCL}$-100		ns
t_{RLDV}	$\overline{RD}$ Low to Valid Data In		147		$5t_{CLCL}$-165	ns
t_{RHDX}	Data Hold After $\overline{RD}$	0		0		ns
t_{RHDZ}	Data Float After $\overline{RD}$		65		$2t_{CLCL}$-60	ns
t_{LLDV}	ALE Low to Valid Data In		350		$8t_{CLCL}$-150	ns
t_{AVDV}	Address to Valid Data In		397		$9t_{CLCL}$-165	ns
t_{LLWL}	ALE Low to $\overline{RD}$ or $\overline{WR}$ Low	137	239	$3t_{CLCL}$-50	$3t_{CLCL}$+50	ns
t_{AVWL}	Address to $\overline{RD}$ or $\overline{WR}$ Low	122		$4t_{CLCL}$-130		ns
t_{QVWX}	Data Valid to $\overline{WR}$ Transition	13		t_{CLCL}-50		ns
t_{QVWH}	Data Valid to $\overline{WR}$ High	287		$7t_{CLCL}$-150		ns
t_{WHQX}	Data Hold After $\overline{WR}$	13		t_{CLCL}-50		ns
t_{RLAZ}	$\overline{RD}$ Low to Address Float		0		0	ns
t_{WHLH}	$\overline{RD}$ or $\overline{WR}$ High to ALE High	23	103	t_{CLCL}-40	t_{CLCL}+40	ns

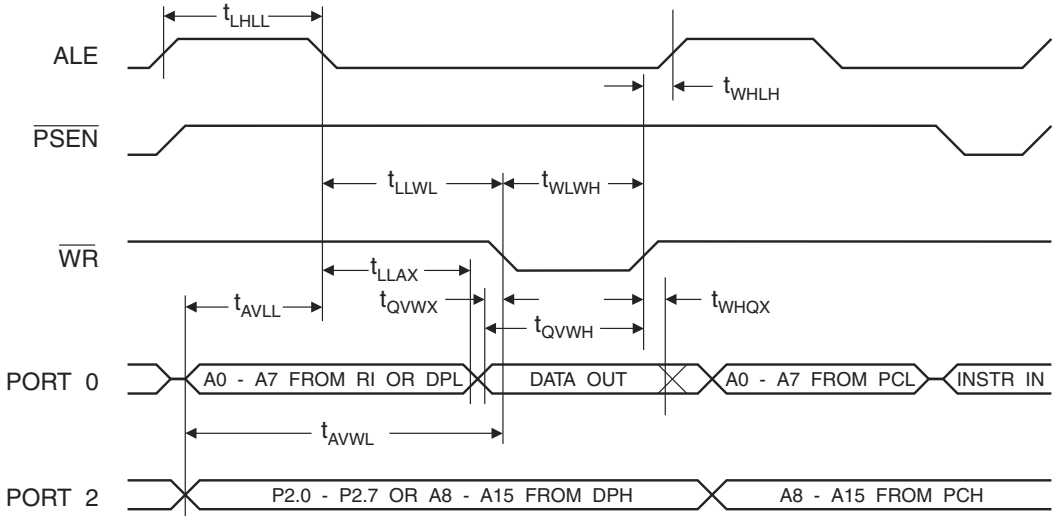
24. External Program Memory Read Cycle



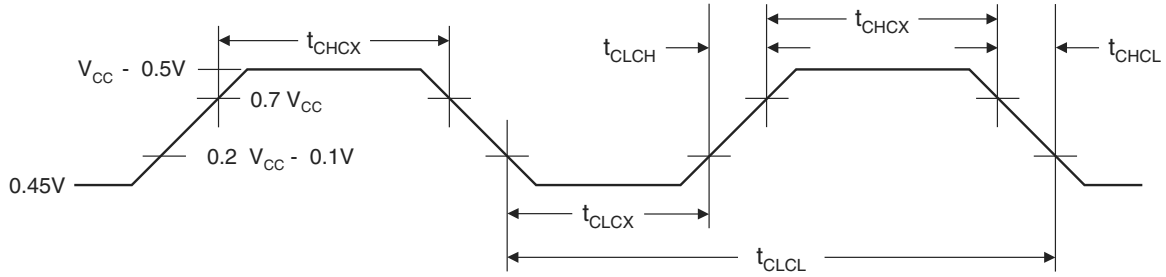
25. External Data Memory Read Cycle



26. External Data Memory Write Cycle



27. External Clock Drive Waveforms



28. External Clock Drive

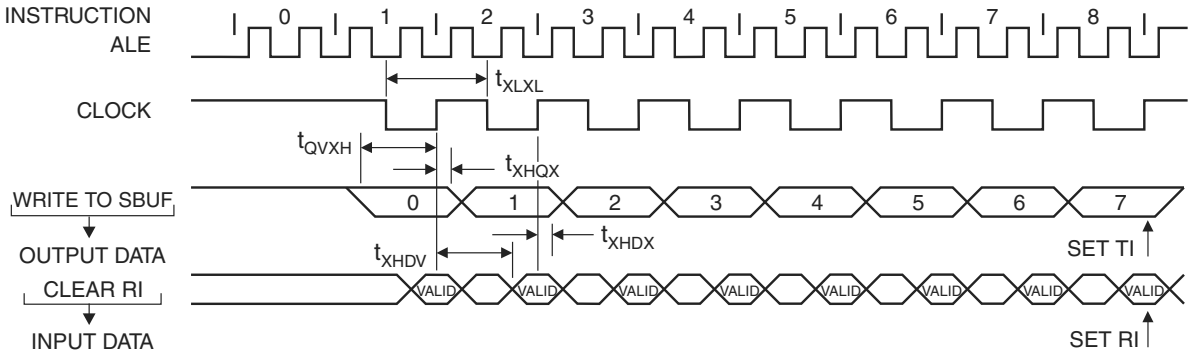
Symbol	Parameter	Min	Max	Units
$1/t_{CLCL}$	Oscillator Frequency	0	16	MHz
t_{CLCL}	Clock Period	62.5		ns
t_{CHCX}	High Time	20		ns
t_{CLCX}	Low Time	20		ns
t_{CLCH}	Rise Time		20	ns
t_{CHCL}	Fall Time		20	ns

29. Serial Port Timing: Shift Register Mode Test Conditions

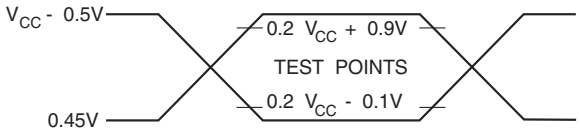
The values in this table are valid for V_{CC} = 2.7V to 4.0V and Load Capacitance = 80 pF.

Symbol	Parameter	12 MHz Osc		Variable Oscillator		Units
		Min	Max	Min	Max	
t_{XLXL}	Serial Port Clock Cycle Time	1.0		$12t_{CLCL}$		µs
t_{QVXH}	Output Data Setup to Clock Rising Edge	700		$10t_{CLCL}$-133		ns
t_{XHQX}	Output Data Hold After Clock Rising Edge	50		$2t_{CLCL}$-80		ns
t_{XHDX}	Input Data Hold After Clock Rising Edge	0		0		ns
t_{XHDV}	Clock Rising Edge to Input Data Valid		700		$10t_{CLCL}$-133	ns

30. Shift Register Mode Timing Waveforms

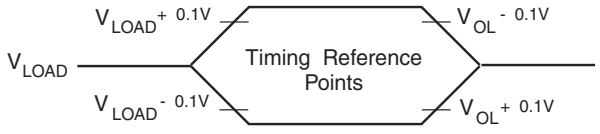


31. AC Testing Input/Output Waveforms(1)



Note: 1. AC Inputs during testing are driven at V_{CC} - 0.5V for a logic 1 and 0.45V for a logic 0. Timing measurements are made at V_{IH} min. for a logic 1 and V_{IL} max. for a logic 0.

32. Float Waveforms(1)



Note: 1. For timing purposes, a port pin is no longer floating when a 100 mV change from load voltage occurs. A port pin begins to float when a 100 mV change from the loaded V_{OH}/V_{OL} level occurs.

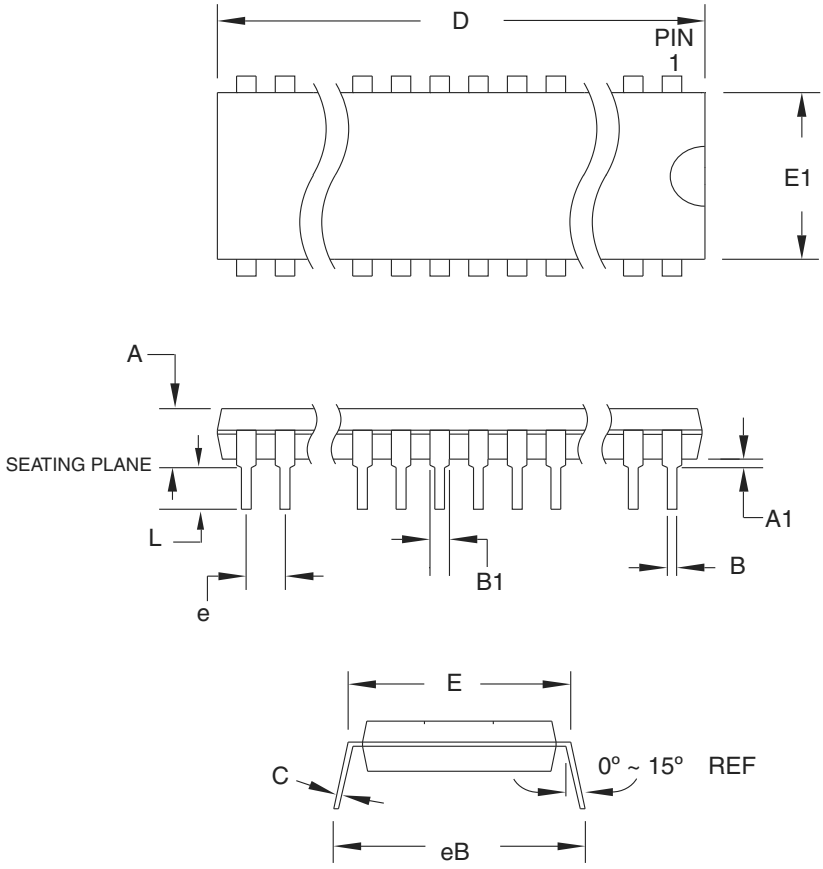
33. Ordering Information

33.1 Green Package Option (Pb/Halide-free)

Speed (MHz)	Power Supply	Ordering Code	Package	Operation Range
16	2.7V to 4.0V	AT89LS51-16AU AT89LS51-16JU AT89LS51-16PU	44A 44J 40P6	Industrial (-40° C to 85° C)

Package Type	
44A	44-lead, Thin Plastic Gull Wing Quad Flatpack (TQFP)
44J	44-lead, Plastic J-leaded Chip Carrier (PLCC)
40P6	40-pin, 0.600" Wide, Plastic Dual Inline Package (PDIP)

34.3 40P6 – PDIP



COMMON DIMENSIONS
(Unit of Measure = mm)

SYMBOL	MIN	NOM	MAX	NOTE
A	–	–	4.826	
A1	0.381	–	–	
D	52.070	–	52.578	Note 2
E	15.240	–	15.875	
E1	13.462	–	13.970	Note 2
B	0.356	–	0.559	
B1	1.041	–	1.651	
L	3.048	–	3.556	
C	0.203	–	0.381	
eB	15.494	–	17.526	
e	2.540 TYP			

Notes: 1. This package conforms to JEDEC reference MS-011, Variation AC.
2. Dimensions D and E1 do not include mold Flash or Protrusion. Mold Flash or Protrusion shall not exceed 0.25 mm (0.010").

09/28/01

	TITLE	DRAWING NO.	REV.
2325 Orchard Parkway San Jose, CA 95131	**40P6**, 40-lead (0.600"/15.24 mm Wide) Plastic Dual Inline Package (PDIP)	40P6	B

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